

Amendments to the Claims

1. (CURRENTLY AMENDED) A lead-frame configuration ~~(60)~~ that is strip-like in form, that has a frame base ~~(3)~~ and that has a plurality of lead-frames ~~(6, 7, 8, 9, 10, 11)~~ that are connected to the frame base ~~(3)~~ and that are situated next to one another in the longitudinal direction ~~(2)~~ of the strip, each of which lead-frames ~~(6, 7, 8, 9, 10, 11)~~ is intended to receive a chip ~~(41, 42, 43, 44, 45, 46)~~, wherein each lead-frame ~~(6, 7, 8, 9, 10, 11)~~ has at least two connecting plates ~~(12, 13)~~, wherein there being is provided for the lead-frames ~~(6, 7, 8, 9, 10, 11)~~ that are situated next to one another in the longitudinal direction ~~(2)~~ of the lead-frame strip a reinforcement strip ~~(66, 67)~~ that extends in the longitudinal direction ~~(2)~~ of the strip and is connected both to the frame base ~~(3)~~ and to the connecting plates ~~(12, 13)~~ of each of the lead-frames ~~(6, 7, 8, 9, 10, 11)~~ that are situated next to one another in the longitudinal direction ~~(2)~~ of the lead-frame strip, the connection being made by means of a layer ~~(73)~~ of adhesive, wherein the reinforcement strip ~~(66, 67)~~ is formed by a fiber-reinforced film of plastics material and wherein the layer ~~(73)~~ of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may possibly occur in the region between the connecting plates ~~(12, 13)~~ on the one hand and the reinforcement strip ~~(66, 67)~~ on the other hand.

2. (ORIGINAL) A lead-frame configuration as claimed in claim 1, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material.

3. (CURRENTLY AMENDED) A lead-frame configuration ~~(60)~~ as claimed in claim 2, wherein at least one further layer is provided on the reinforcement strip formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers detailed below, which group comprises: a protective layer that is composed of metal, a damping layer that is composed of a damping material and preferably of a paper-like material, and a fastening layer that is composed of a fastening material and preferably of an adhesive material.

4. (CURRENTLY AMENDED) A module ~~(70)~~ that is produced with the help of a lead-frame configuration ~~(60)~~ and that has at least two connecting plates ~~(12, 13)~~ each of which is connected to a connecting contact ~~(47, 48)~~ of a chip ~~(41)~~, and that has a reinforcement ribbon ~~(71)~~ that is connected to the connecting plates ~~(12, 13)~~, the connection being made by means of a layer ~~(73)~~ of adhesive, wherein the reinforcement ribbon ~~(71)~~ is formed by a fiber-reinforced film of plastics material and wherein the layer ~~(73)~~ of adhesive is produced by means of an adhesive that is suitable for transmitting shear forces that may possibly occur in the region between the connecting plates ~~(12, 13)~~ on the one hand and the reinforcement ribbon ~~(71)~~ on the other hand.

5. (CURRENTLY AMENDED) A module ~~(70)~~ as claimed in claim 4, wherein at least one further layer ~~(74, 75, 76)~~ is provided on the reinforcement ribbon ~~(71)~~ formed by a fiber-reinforced film of plastics material.

6. (CURRENTLY AMENDED) A module ~~(70)~~ as claimed in claim 5, wherein at least one further layer ~~(74, 75, 76)~~ is provided on the reinforcement ribbon ~~(71)~~ formed by a fiber-reinforced film of plastics material, which at least one further layer belongs to the group of layers ~~(74, 75, 76)~~ detailed below, which group comprises: a protective layer ~~(74)~~ that is composed of metal, a damping layer ~~(75)~~ that is composed of a damping material and preferably of a paper-like material, and a fastening layer ~~(76)~~ that is composed of a fastening material and preferably of an adhesive material.

7. (CURRENTLY AMENDED) A data carrier ~~(72)~~, wherein the data carrier ~~(72)~~ contains a module as claimed in any of claims 4 to 6 claim 4.